



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ0502NSI	Issued	30. March 2021
MA#	MA001300030		
Package	PG-TSDSON-8-25	Weight*	34.56 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.326	0.94	0.94	9433	9433
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		105	
	non noble metal	zinc	7440-66-6	0.015	0.04		421	
	non noble metal	iron	7439-89-6	0.291	0.84		8411	
	non noble metal	copper	7440-50-8	11.804	34.15	35.04	341538	350475
wire	non noble metal	copper	7440-50-8	0.017	0.05	0.05	478	478
encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		1049	
	plastics	epoxy resin	-	1.867	5.40		54022	
	inorganic material	silicondioxide	60676-86-0	16.224	46.96	52.46	469413	524484
leadfinish	non noble metal	tin	7440-31-5	0.395	1.14	1.14	11436	11436
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	588	588
solder	non noble metal	tin	7440-31-5	0.011	0.03		305	
	noble metal	silver	7440-22-4	0.013	0.04		381	
	non noble metal	lead	7439-92-1	0.503	1.46	1.53	14562	15248
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			26	
	non noble metal	zinc	7440-66-6	0.004	0.01		105	
	non noble metal	iron	7439-89-6	0.073	0.21		2109	
	non noble metal	copper	7440-50-8	2.959	8.56	8.78	85618	87858
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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